


T-6000-L/G



- Best bonding performance in the market
- Designed for tomorrow's semiconductor needs
- One machine, unlimited bonding processes
- Made in Germany 

The T-6000-L/G DIE Bonder combines precision with customization and speed.

It is built on a granite gantry to achieve the highest level of bonding accuracy.

The ultimate bonding platform from prototyping to volume production.

The T-6000-L/G the unmatched level of modularity and flexibility.

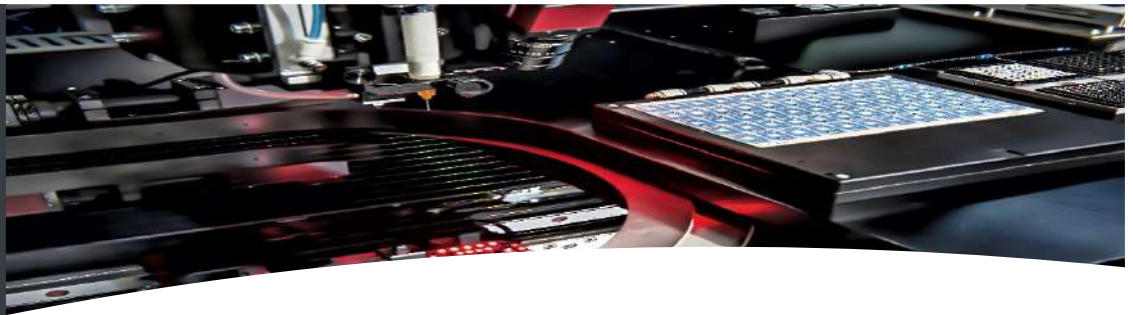
Unique manual mode for instant DIE bonding.

Technical Data

Travel Range with Wafer	410 mm x 420 mm
Wafer Size	2" – 8" (Ring & Frame)
Travel Range w/o Wafer	550 mm x 420 mm
Z-Movement	100 mm
Chip Rotation max.	up to 360°
Bond Force Range	10 g – up to 10.000 g *
Axis Speed	up to 1.8 m/sec
Placement Accuracy	2.5 µm @ 3 sigma
Axis Resolution	XYZ: 0.01 µm, Theta: 0.01°
Min./Max. Component Size	80 µm – 100 mm **

* Higher bond force on request

** Other dimensions on request | Note: All specifications are subject to change without notice



DIE Attach Technologies

- Micro Assembly
- Eutectic Bonding
- Stamping
- Ultrasonic Bonding
- Flip Chip Bonding
- Thermosonic Bonding
- Thermocompression Bonding
- Flux Dipping
- Adhesive Bonding
- DIE Stacking

Applications (Customer Specific)

- DTF / DAF Bonding
- Multi DIE Bonding
- MEMS
- SMD Bonding
- 3D Packaging (SiP)
- Laser Bar Stacking
- Glas Frit Bonding
- TO Header Bonding
- Vcsel Bonding
- RFID Assembly
- DIE Sorting

Modules & Options

- Wafer Table with DIE Ejector
- UV Indexer
- WRGB Light
- Heating Plates
 - Up to 450°C
 - Ramp rates up to 60 K/s
- Inert Gas Protection
- Automatic Tool Change
- Several Dispensing Options
- Stamping Unit
- Tool Heating
- Feeder Unit
- Uplooking Camera
- ID Scanner
- DIE Flipping Unit
- Pre-heated Inert Gas
- Automatic Wafer Change
- Conveyor / Magazine Lifter
- Inline Production

Features

- Manual Mode
- Multichip Application Capability
- Post Bond Inspection
- Software integrated temp. Control
- Wafer Mapping
- OCR
- Traceability
- MES
- Automatic Dispense Needle Calibration
- Customer Specific Workspace
- Scrubbing
- Pattern Recognition Methods
- Deep Access Bonding (15 mm)
- Preform Cutter

Contact

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For more informations:

